

Abstract of the Disclosure

A method for manufacturing a thin film includes the steps of loading a substrate into a reaction chamber, and terminating the surface of the substrate loaded into the reaction chamber by a specific atom. A first reactant is chemically adsorbed on the terminated substrate by injecting the first reactant into the reaction chamber including the terminated substrate. After removing the first reactant physically adsorbed into the terminated substrate, a solid thin film is formed through chemical exchange or reaction of the chemically adsorbed first reactant and a second reactant by injecting the second reactant into the reaction chamber. According to the thin film manufacturing method according to the present invention, it is possible to grow a thin film on the substrate in a state in which the no or little impurities and physical defects are generated in the thin film and interface of the thin film.